

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary

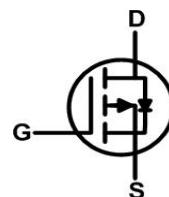
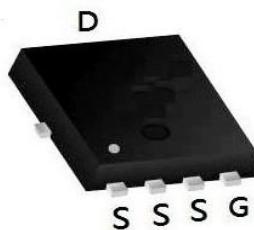
BVDSS	RDS(ON)	ID
-30V	3.5mΩ	-90 A

### Description

The XXW90P03DF is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The XXW90P03DF meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### PRPAK5X6 Pin Configuration



### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current  $T_C=25^\circ\text{C}$	$I_D$	-90	A
		-57	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-360	A
Single Pulse Avalanche Energy <sup>2</sup>	EAS	125	mJ
Total Power Dissipation	$P_D$	60	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	55	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	2.08	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-30	-	-	V
Gate-body Leakage current	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$ $T_J=100^\circ\text{C}$	$I_{DSS}$	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$	-	-	-1	$\mu\text{A}$
			-	-	-100	
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance <sup>4</sup>	$R_{DS(\text{on})}$	$V_{GS} = -10\text{V}, I_D = -30\text{A}$	-	3.5	4.5	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -15\text{A}$	-	4.8	6.2	
Forward Transconductance <sup>4</sup>	$g_{fs}$	$V_{DS} = -10\text{V}, I_D = -30\text{A}$	-	90	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	5070	-	$\text{pF}$
Output Capacitance	$C_{oss}$		-	695	-	
Reverse Transfer Capacitance	$C_{rss}$		-	580	-	
Gate resistance	$R_g$	$f = 1\text{MHz}$	-	4	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{GS} = -10\text{V}, V_{DS} = -15\text{V}, I_D = -30\text{A}$	-	146	-	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		-	21.5	-	
Gate-Drain Charge	$Q_{gd}$		-	39	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = -10\text{V}, V_{DD} = -15\text{V}, R_G = 3\Omega, I_D = -30\text{A}$	-	23	-	$\text{ns}$
Rise Time	$t_r$		-	15	-	
Turn-Off Delay Time	$t_{d(off)}$		-	129	-	
Fall Time	$t_f$		-	28	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{SD}$	$I_S = -30\text{A}, V_{GS} = 0\text{V}$	-	-	-1.2	V
Continuous Source Current	$T_c=25^\circ\text{C}$	$I_S$	-	-	-90	A

Note :

- Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$
- The EAS data shows Max. rating . The test condition is  $V_{DD} = -25\text{V}, V_{GS} = -10\text{V}, L = 0.1\text{mH}, I_{AS} = -50\text{A}$
- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

## Typical Characteristics

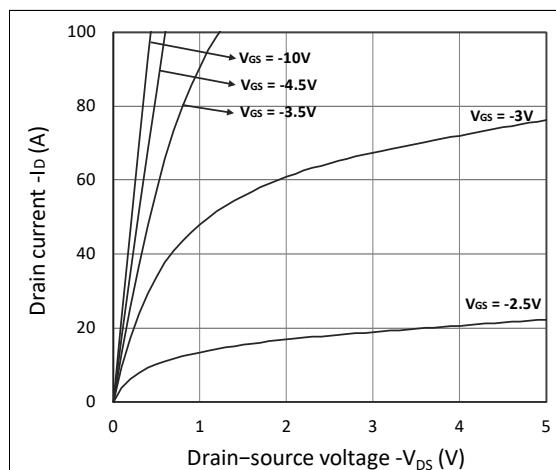


Figure 1. Output Characteristics

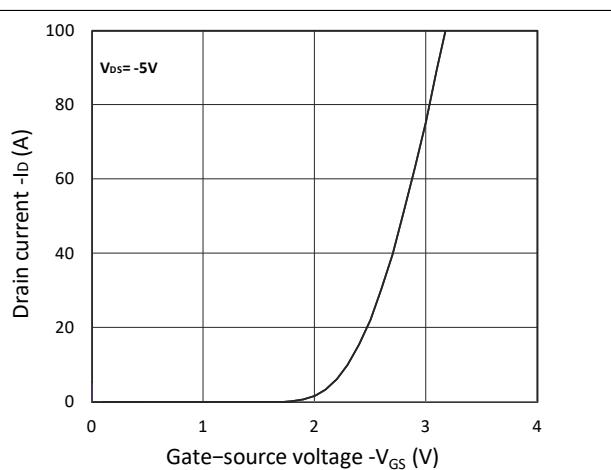


Figure 2. Transfer Characteristics

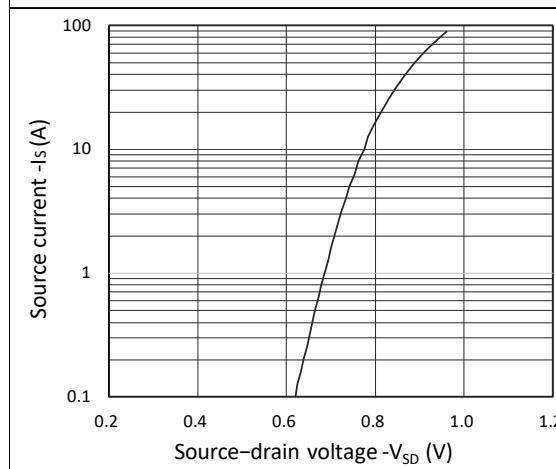


Figure 3. Forward Characteristics of Reverse

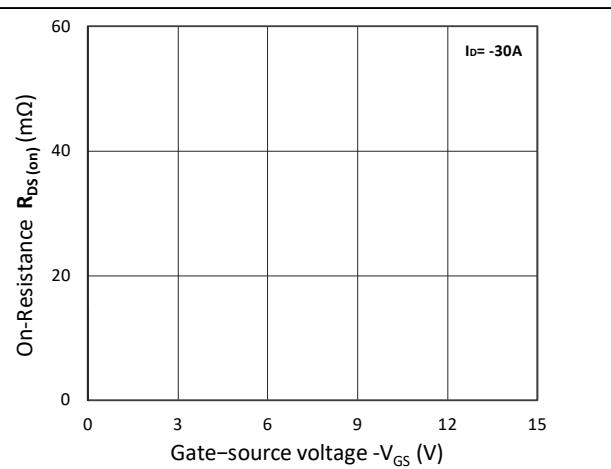


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

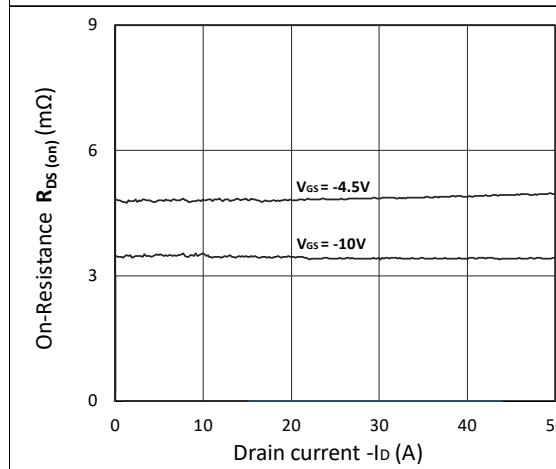


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

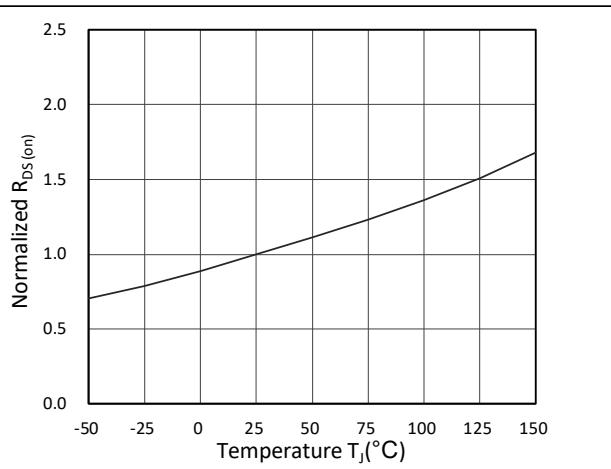


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

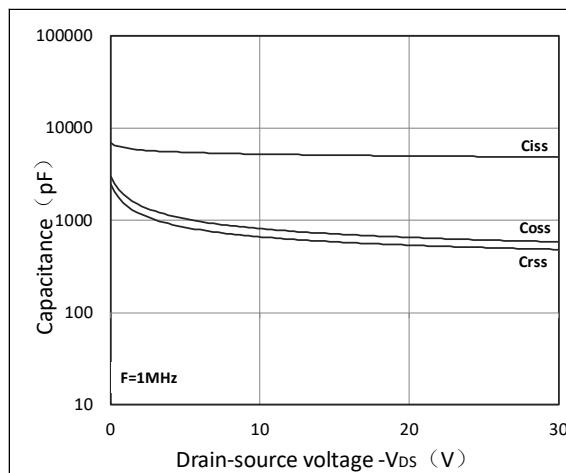


Figure 7. Capacitance Characteristics

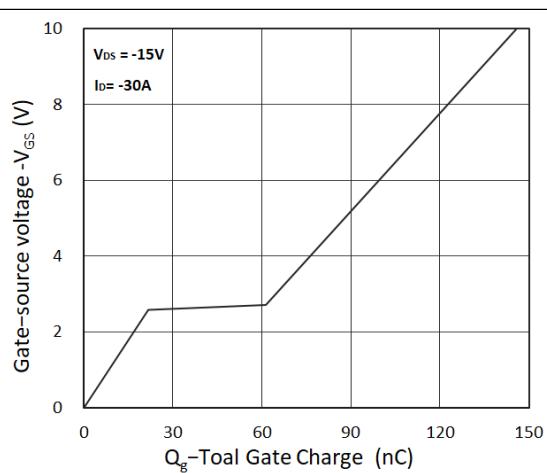


Figure 8. Gate Charge Characteristics

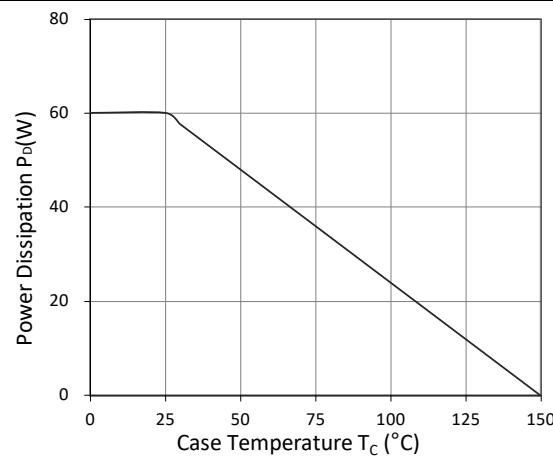


Figure 9. Power Dissipation

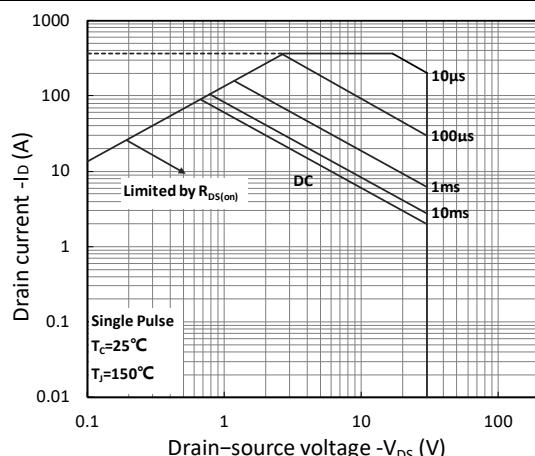


Figure 10. Safe Operating Area

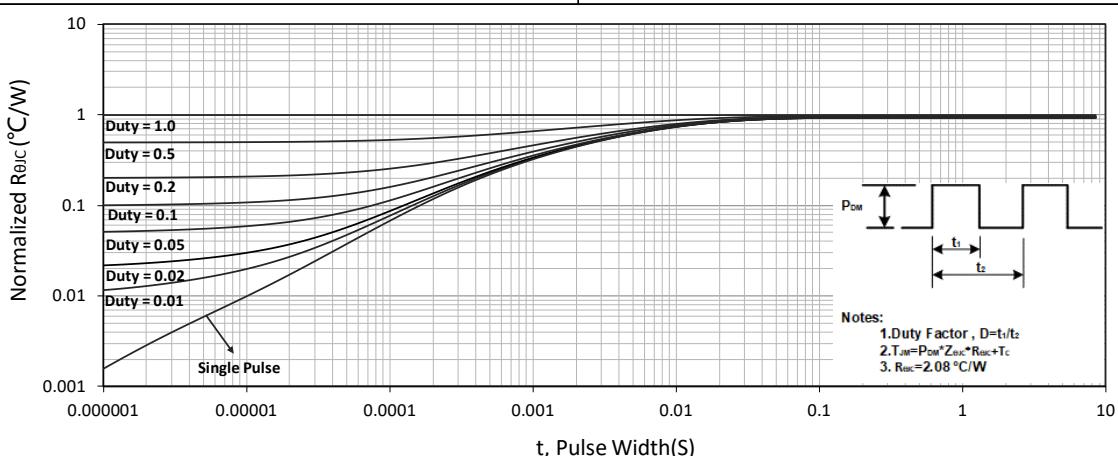
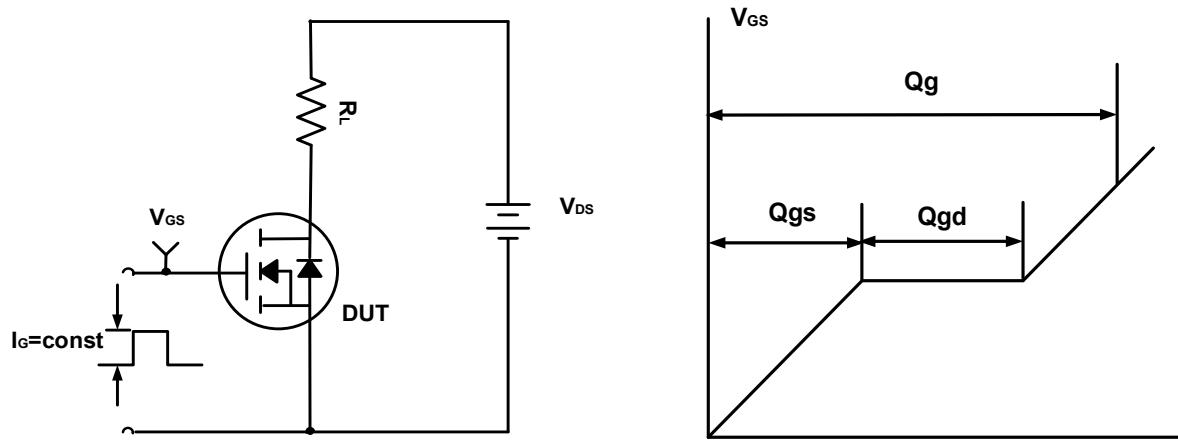
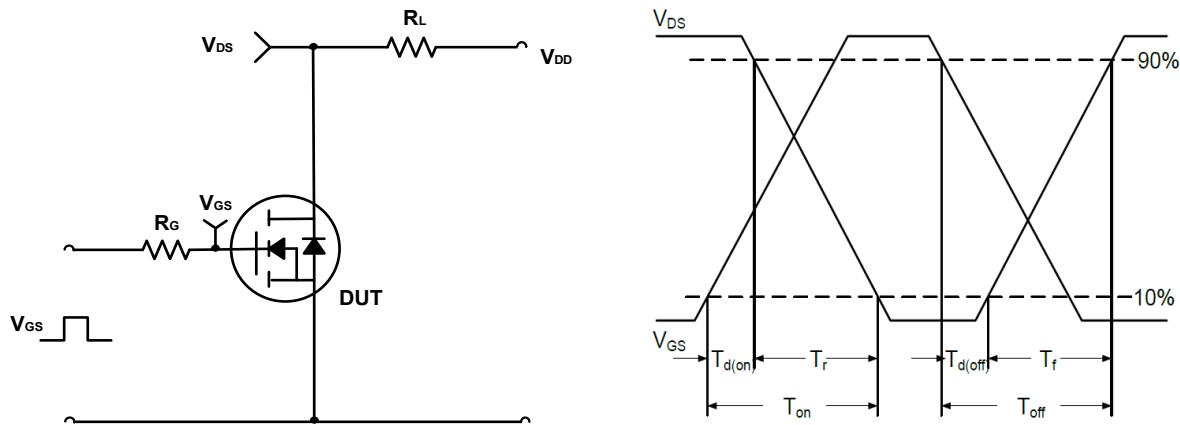
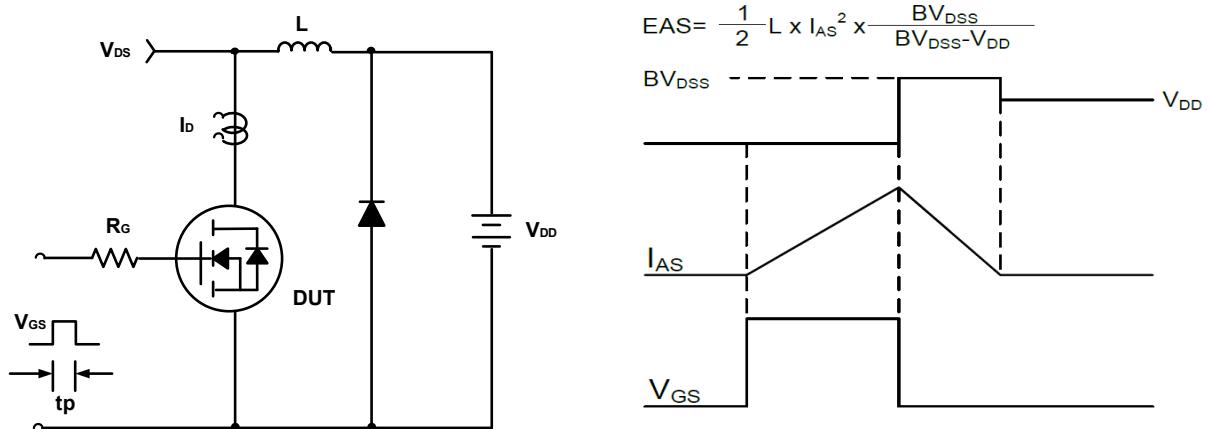
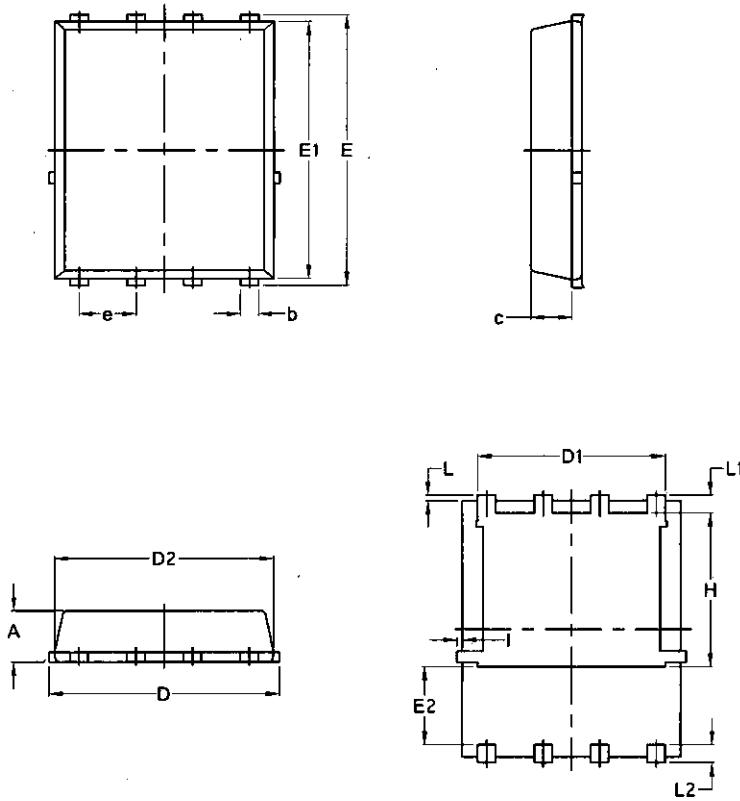


Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit**

**Figure A. Gate Charge Test Circuit & Waveforms**

**Figure B. Switching Test Circuit & Waveforms**

**Figure C. Unclamped Inductive Switching Circuit & Waveforms**

**Package Mechanical Data-DFN5\*6-8L-JQ Single**


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070